

TPT application: bonding of aluminum-coated copper wire

Here we present a special bond application: wedge bonding with aluminum-coated copper wire.

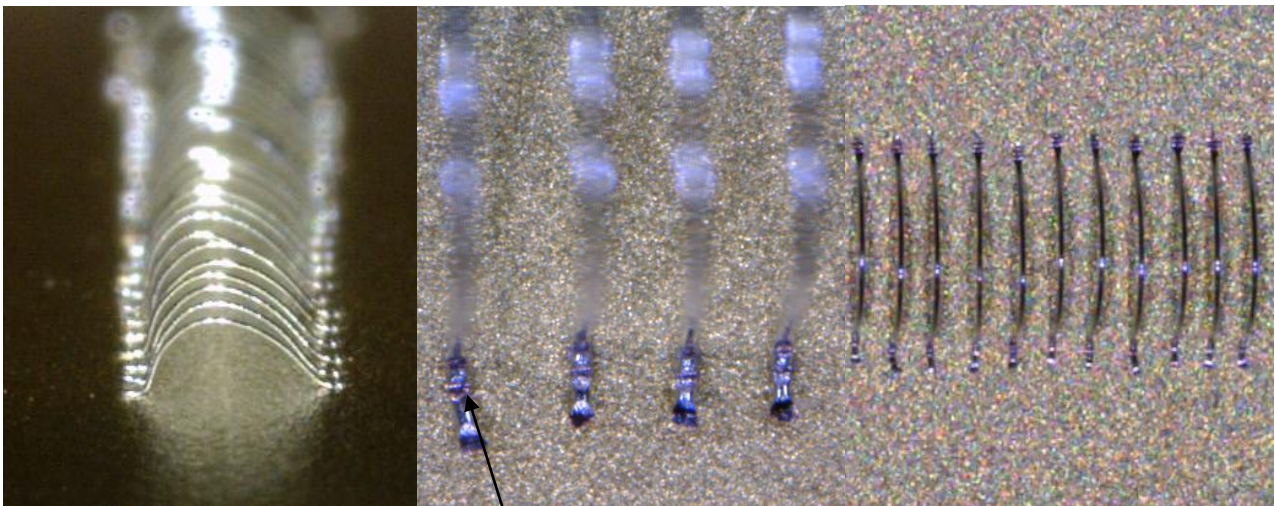
Overview:

Copper wires have bonding characteristics similar to gold, but have to be handled in an inert atmosphere due to the oxidation. Because of this effort copper wires are only used if there is a special requirement to do so.

A user-friendly alternative is copper wire with aluminum coating. This wire can be easily wedge bonded and has good storage characteristics.

Equipment:

- 25 μ copper-wire (Cu-HC4) sputtered with a aluminum layer of 20 – 30 nm
- Standard 25 μ gold wedge
- Semi-automatic wedge bonder HB16



wedge bonds

slight copper color visible in the bond mark

Bonding process:

- The wire can be bonded & handled like 25 μ gold wire.



TPT Wire Bonder

Tel: +49 8131 / 58604

Email: info@tpt.de

Web: www.tpt.de

